



Frontier Electronics Corp.

667 E. COCHRAN STREET, SIMI VALLEY, CA 93065

TEL: (805) 522-9998 FAX: (805) 522-9989

E-mail: frontiersales@frontierusa.com

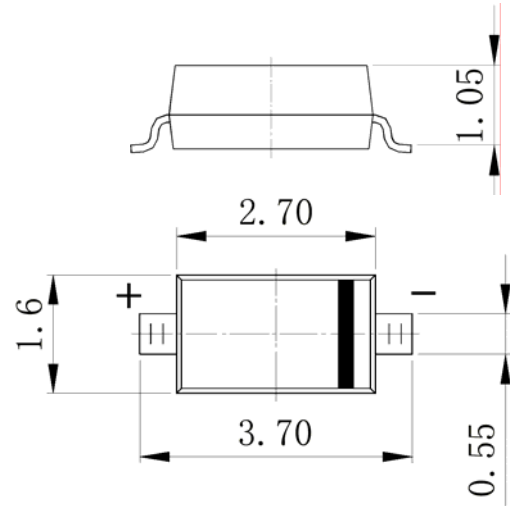
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ZENER DIODES

MMSZ5221B THRU MMSZ5259B

FEATURES

- PLANAR DIE CONSTRUCTION
- ULTRA-SMALL SURFACE MOUNT PACKAGE
- GENERAL PURPOSE, MEDIUM CURRENT
- IDEALLY SUITED FOR AUTOMATED ASSEMBLY PROCESSES



CASE: SOD-123

UNIT:MM

MAXIMUM RATINGS ($T_{AMB}=25^{\circ}C$ UNLESS OTHERWISE SPECIFIED)

CHARACTERISTIC	SYMBOL	VALUE	UNIT
FORWARD VOLTAGE $I_F=10mA$	V_F	0.9	V
POWER DISSIPATION (NOTE1)	P_d	350	mW
THERMAL RESISTANCE , JUNCTION TO AMBIENT AIR (NOTE1)	$R_{\theta JA}$	357	K/W
OPERATING AND STORAGE TEMPERATURE RANGE	$T_{I,TSTG}$	- 65 TO + 150	$^{\circ}C$

NOTE: 1. VALID PROVIDED THAT DEVICE TERMINALS ARE KEPT AT AMBIENT TEMPERATURE.

2. TESTED WITH PULSES , $T_p \leq 1.0ms$

ELECTRICAL CHARACTERISTICS (At T_A =25°C UNLESS OTHERWISE SPECIFIED)

TYPE NUMBER	TYPE CODE	ZENER VOLTAGE RANGE (NOTE 2)				MAXIMUM ZENER IMPEDANCE			MAXIMUM REVERSE LEAKAGE CURRENT	
		VZ@IZT			IZT	ZZT@IZT	ZZK@IZK	IZK	IR	VR
		NOM(V)	MIN(V)	MAX(V)	mA	Ω		mA	uA	V
MMSZ5221B	C1	2.4	2.28	2.52	20	30	1200	0.25	100	1.0
MMSZ5223B	C3	2.7	2.57	2.84	20	30	1300	0.25	75	1.0
MMSZ5225B	C5	3.0	2.85	3.15	20	30	1600	0.25	50	1.0
MMSZ5226B	G1	3.3	3.14	3.47	20	28	1600	0.25	25	1.0
MMSZ5227B	G2	3.6	3.42	3.78	20	24	1700	0.25	15	1.0
MMSZ5228B	G3	3.9	3.71	4.10	20	23	1900	0.25	10	1.0
MMSZ5229B	G4	4.3	4.09	4.52	20	22	2000	0.25	5.0	1.0
MMSZ5230B	G5	4.7	4.47	4.94	20	19	1900	0.25	5.0	2.0
MMSZ5231B	E1	5.1	4.85	5.36	20	17	1600	0.25	5.0	2.0
MMSZ5232B	E2	5.6	5.32	5.88	20	11	1600	0.25	5.0	3.0
MMSZ5233B	E3	6.0	5.70	6.30	20	7	1600	0.25	5.0	3.5
MMSZ5234B	E4	6.2	5.89	6.51	20	7	1000	0.25	5.0	4.0
MMSZ5235B	E5	6.8	6.46	7.14	20	5	750	0.25	3.0	5.0
MMSZ5236B	F1	7.5	7.13	7.88	20	6	500	0.25	3.0	6.0
MMSZ5237B	F2	8.2	7.79	8.61	20	8	500	0.25	3.0	6.5
MMSZ5238B	F3	8.7	8.27	9.14	20	8	600	0.25	3.0	6.5
MMSZ5239B	F4	9.1	8.65	9.56	20	10	600	0.25	3.0	7.0
MMSZ5240B	F5	10	9.50	10.50	20	17	600	0.25	3.0	8.0
MMSZ5241B	H1	11	10.45	11.55	20	22	600	0.25	2.0	8.4
MMSZ5242B	H2	12	11.40	12.60	20	30	600	0.25	1.0	9.1
MMSZ5243B	H3	13	12.35	13.65	9.5	13	600	0.25	0.5	9.9
MMSZ5245B	H5	15	14.25	15.75	8.5	16	600	0.25	0.1	11
MMSZ5246B	J1	16	15.20	16.80	7.8	17	600	0.25	0.1	12
MMSZ5248B	J3	18	17.10	18.90	7.0	21	600	0.25	0.1	14
MMSZ5250B	J5	20	19.00	21.00	6.2	25	600	0.25	0.1	15
MMSZ5251B	K1	22	20.90	23.10	5.6	29	600	0.25	0.1	17
MMSZ5252B	K2	24	22.80	25.20	5.2	33	600	0.25	0.1	18
MMSZ5254B	K4	27	25.65	28.35	5.0	41	600	0.25	0.1	21
MMSZ5255B	K5	28	26.60	29.40	4.5	44	600	0.25	0.1	21
MMSZ5256B	M1	30	28.50	31.50	4.2	49	600	0.25	0.1	23
MMSZ5257B	M2	33	31.35	34.65	3.8	58	700	0.25	0.1	25
MMSZ5258B	M3	36	34.20	37.80	3.4	70	700	0.25	0.1	27
MMSZ5259B	M4	39	37.05	40.95	3.2	80	800	0.25	0.1	30

NOTE: 1. DEVICE MOUNTED ON CERAMIC PCB ; 7.6mm x 9.4mm x 0.87mm WITH PAD AREAS 25 mm².
 2. TESTED WITH PULSES , T_p ≤ 1.0ms.

FIG. 1 –FORWARD DISSIPATION VS AMBIENT TEMPERATURE

